

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re the Application of:

Abbott, et al.

Serial No.: 09/733,718

Filed: 12/08/00

For: LEADFRAMES FOR HIGH ADHESION SEMICONDUCTOR DEVICES  
AND METHOD OF FABRICATION (as amended)

Docket No.: TI-29679

Examiner: Cao, Phat X.

Art Unit: 2496

Amendment under 37 CFR 1.111

Assistant Commissioner of Patents  
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the  
U.S. Postal Service as First Class Mail in an envelope addressed to:  
Assistant Commissioner for Patents, Washington, D.C. 20231 on

6-26-02

*Marianna Smith*  
Marianna Smith

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 03/26/02. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

Please amend the above-referenced application as follows:

In the Title:

LEADFRAMES FOR HIGH ADHESION SEMICONDUCTOR DEVICES AND  
METHOD OF FABRICATION